Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: SR0102-03 REV. 1 DATE: 7/16/01
Product Affected: SRAM 1M Product Family
Refer to attached list.
Manufacturing Location Affected: Salinas, California
Date Effective: 7/16/01

MEANS OF DISTINGUISHING CHANGED DEVICES:
- ☐ Product Mark
- ☐ Back Mark
- ☐ Date Code
- ■ Other

Traceability to wafer Fab is through Assembly lot number

Contact: George Snell
Title: Quality Assurance Manager
Phone #: (831) 754-4556
Fax #: (831) 754-4672
E-mail: george.snell@idt.com

Attachment:: ☐ Yes ■ No

Samples: Contact the local IDT sales representative

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ■ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

Transfer existing qualified product from Hillsboro, Oregon (Fab 4) to Salinas, California (Fab 2) to enhance Fab capacity loading. Refer to attached change matrix for each product transfer details.

REV.1 Top mark will not be used to distinguish manufacturing site as shown on original PCN. Traceability to the wafer Fab is maintained in the Assembly lot number. Assembly Lot number is marked on the device. IDT may manufacture these products in either qualified Fab facility.

RELIABILITY/QUALIFICATION SUMMARY:

Qualification of each product will verify that there is no impact to quality or reliability of the product.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ______________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ______________________

E-Mail Address: ______________________

Title: ______________________

Phone# /Fax# : ______________________

CUSTOMER COMMENTS: ______________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ______________________ DATE: ______________________

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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: SR0102-03 REV. 1

PCN Summary
PCN Type: Fab Site Change

Commodity Memory

Forecast or Execute Execute

Planned or Unplanned Unplanned

Data Sheet Change None Expected

Detail of Change

Transfer existing or duplicate reticle sets of qualified products to the Salinas, Califormia Wafer Fab Facility from Hillsboro, Oregon Wafer Fab Facility.

		Current Wafer Fab			Transfer Wafer Fab		
Part Name	Technology	Manufacturing Site	Wafer Size	Die Revison	Manufacturing Site	Wafer Size	Die Revison
71024S	Cmos 9	Hillsboro, OR	8 inch	M	Salinas, CA	6 inch	L
71028S	Cmos 9	Hillsboro, OR	8 inch	M	Salinas, CA	6 inch	L
71016S	Cmos 9	Hillsboro, OR	8 inch	N	Salinas, CA	6 inch	N
71124S	Cmos 9	Hillsboro, OR	8 inch	N	Salinas, CA	6 inch	N
71128S	Cmos 9	Hillsboro, OR	8 inch	N	Salinas, CA	6 inch	N

Conversion schedule (Estimated)

	First Production Shipments
71024S	May 28, 2001
71028S	May 28, 2001
71016S	May 28, 2001
71124S	May 28, 2001
71128S	May 28, 2001